ABSTRACT

METHOD OF CONNECTING TAB TAPE TO SEMICONDUCTOR CHIP, AND BUMP SHEET AND BUMPED TAPE USED IN THE METHOD

A method of connecting a TAB tape (12) to a semiconductor chip (1) is disclosed which comprises the steps of preliminarily locating and fixing bumps (6) at positions corresponding to a pattern of electrodes (7) of the semiconductor chip to be connected; and bonding the bumps by thermocompression to the electrodes of the semiconductor chip and the leads (2) of the TAB tape, respectively, so that each electrode of the semiconductor chip is electrically connected to the corresponding lead of the TAB tape through a corresponding one of the bumps. Also disclosed are a bump sheet (11) and a bumped tape to be used in a method of connecting a TAB tape to a semiconductor chip.

This Sheet Has Been Replaced

